ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES®	© Co	terial Compo pyright 2005. IPC, Bannock nternational and Pan-Americ	burn, Illinois	. All rights reserve	tion with lower	r level p	arts, the	declaratio	n encom	passes a	all lower l	evel mate	erials for	which th	e item is an assembly ne manufacturer has leclaration.	
1752-2 1.1		Web Site for Informati		-1752 Standa		n Type * ribute			claration Class * ss 6 - RoHS Yes/No, Homogeneous Materials and Mfg Informa							
Supplier Information																
Company Name *		Company Unique ID		Unique ID Au	Respo	Response Date *				Response Document ID						
Anaren Microwave						2020-0	06-16									
Contact Name * Title - Contact				Phone - Con	Email	- Contac	t *		-	1	2 , ,	Δ (1		1		
Herbert Jones Project Engineer				315-233-5510			herbert.jones@ttm.com				Duplicate Contact -> Authorized Representative					
Authorized Representative * Title - Representative			Phone - Rep	Email	Email - Representative *				Supplier Comments or URL for Additional Information							
Herbert Jones Project Engineer				315-233-551	herbe	rt.jones@	ttm.con	n								
Requester Item Number		Mfr Item Number	Mfr Item Name	Effective Date Version			Manufacturing Site		e v	Veight *	UC	M	Unit Type			
		XRA10AA1SES		Termination		2020-		A	Suzhou	, China	hina 0.0236		g		Each	
Alternate Recommenda	ation				Alternate Item (Item Co	Comments							
Manufacturing Proces	ss In	formation														
Terminal Plating / Grid Array	Materi	ial	Terminal B	ase Alloy	J-STD-020 MSL R	ating	Peak Proc	ess Body	Tempera	ture Max	x Time at F	Peak Tem	perature	Number	of Reflow Cycles	
Matte Tin (Sn) - reflowed over Nickel (Ni) barrier Other					1		2				30 Se		econds 3			
Comments		. , ,			1											
Compliant to RoHS 2 Dir	ectiv	e 2011/65/EU of the	Europear	Parliament a	and of the Coun	cil of 8	June 201	1 & Con	nmissio	n Delega	ated Dire	ctive 20°	15/863/E	U of 31	March 2015.	

Save the fields in Import fields from a Clear all of the Lock the fields on this **Export Data** Import Data Reset Form Lock Supplier Fields this form to a file file into this form fields on this form form to prevent changes **RoHS Material Composition Declaration Declaration Type *** Custom Rohs Directive Rohs Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenvls (PBB). Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium 2002/95/EC RoHS 2 (Directive 2011/65/EU & 2015/863/EU) Definition Addendum: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Bis(2-ethylhexyl) phthalate (DEHP), Butyl benzyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP). Supplier certifies that it gathered the information it provides in this form concerning RoHS restrictive substances using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. Supplier Acceptance * Accepted 1 - Item(s) does not contain RoHS restricted substances per the definition above **RoHS Declaration *** Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions. **Declaration Signature**

Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier Digital Signature

Homogeneous Material Composition Declaration for Electronic Products

Subltem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Line Functions: +I Inserts a New Item /SubItem +M Inserts a new Material +C Inserts a new Substance Category +S Inserts a new Substance - Deletes the element line

ı	Item/SubItem		Homogeneous	Weight	Unit of		Lavel	Substance Category			Substance	CAS	Evenue	Waimbt	Unit of	Tolera	nce	PPM
	Name		Material		Measure		Level	Substance Category			Substance	CAS	Exempt	Weight	Measure	-	+	FFIVI
+1 -1 >	(RA10AA1SES	+M -M	Part Marking Ink	0.00001	0 g	+C -C	Supplier	Part Marking Ink	+S	-S	Titanium dioxide (TiO2)	13463-67-7		0.000009	g		8	57,10
						+C -C	Supplier	Part Marking Ink	+S	-S	Silica amorphous (SiO2	7631-86-9		0.000001	g		14	42,90
		+M -M	Protective Glaze	0.00085	7 g	+C -C	Supplier	Protective Glaze	+S	-S	Boron Oxide (BO)	1303-86-2		0.000067	g		78	8,774
						+C -C	Supplier	Protective Glaze	+S	-S	Aluminum Oxide (Al2O3	1344-28-1		0.000020	g		2	23,635
						+C -C	Supplier	Protective Glaze	+S	-S	Silicon Dioxide (SiO2)	14808-60-7		0.000020	g		2	23,635
						+C -C	Supplier	Protective Glaze	+S	-S	*Proprietary Metal Com	Proprietary		0.000054	g		6	3,241
						+C -C	Supplier	Protective Glaze	+S	-S	*Proprietary Blue Pigme	Proprietary		0.000108	g		1:	26,48
						+C -C	Supplier	Protective Glaze	+S	-S	Chromium(III) oxide (Cr	1308-38-9		0.000004	g		5,	5,219.7
						+C -C	Supplier	Protective Glaze	+S	-S	Cobalt (Co)	7440-48-4		0.000162	g		18	89,72
						+C -C	Supplier	Protective Glaze	+S	-S	Molybdenum (Mo)	7439-98-7		0.000216	g		2	252,96
						+C -C	Supplier	Protective Glaze	+S	-S	Zinc oxide (ZnO)	1314-13-2		0.000202	g		2	236,32
		+M -M	Thick Film Resis	0.00009	7 g	+C -C	Supplier	Thick Film Resistor	+S	-S	Boron Oxide (BO)	1303-86-2		0.000013	g		1:	34,60
						+C -C	Supplier	Thick Film Resistor	+S	-S	Magnesium Oxide (MgO	1309-48-4		0.000009	g		90	6,200
						+C -C	Supplier	Thick Film Resistor	+S	-S	Aluminum Oxide (Al2O3	1344-28-1		0.000013	g		1:	34,60
						+C -C	Supplier	Thick Film Resistor	+S	-S	Silicon Dioxide (SiO2)	14808-60-7		0.000005	g		5 ⁻	1,300
						+C -C	Supplier	Thick Film Resistor	+S	-S	Ruthenium(IV) dioxide (12036-10-1		0.000048	g		49	93,60
						+C -C	Supplier	Thick Film Resistor	+S	-S	Zinc oxide (ZnO)	1314-13-2		0.000008	g		89	9,700
		+M -M	Conductor	0.00127	1g	+C -C	Supplier	Conductor	+S	Ģ	Silver (Ag)	7440-22-4		0.001156	g		9	10,00
						+C -C	Supplier	Conductor	+S	-S	Cobalt (Co)	7440-48-4		0.000019	g		1	5,000
						+C -C	Supplier	Conductor	+S	-S	Titanium (Ti)	7440-32-6		0.000095	g		7	5,000
		+M -M	Substrate	0.02106	0 g	+C -C	Supplier	Substrate	+S	-S	Aluminum Nitride (ALN	24304-00-5		0.020007	g		9	50,00
						+C -C	Supplier	Substrate	+S	-s	Yttrium (III) oxide (Y2O3	1314-36-9		0.001053	g		50	50,000
		+M -M	Nickel Plating	0.00033	0 g	+C -C	A	Lead/Lead Compound	+S	-s	Lead	7439-92-1		0.000000	g		4	199.75

		+C -C B	Nickel (external applic	+S ·	-S	Nickel	7440-02-0	0.000330	g		999,50
+M -M Tin Plating	0.00001 0 g	+C -C Supplier	Tin Plating	+8 -	-s	Tin (Sn)	7440-31-5	0.000010	g		1,000,0